

General Description

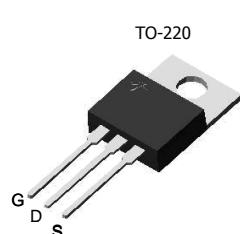
The AOT7N60 & AOTF7N60 have been fabricated using an advanced high voltage MOSFET process that is designed to deliver high levels of performance and robustness in popular AC-DC applications. By providing low $R_{DS(on)}$, C_{iss} and C_{rss} along with guaranteed avalanche capability these parts can be adopted quickly into new and existing offline power supply designs.

For Halogen Free add "L" suffix to part number:
AOT7N60L & AOTF7N60L

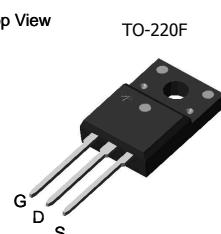
Product Summary

V_{DS}	700V@150°C
I_D (at $V_{GS}=10V$)	7A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 1.2Ω

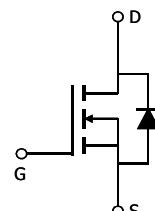
100% UIS Tested
100% R_g Tested



Top View



TO-220F



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	AOT7N60	AOTF7N60	Units
Drain-Source Voltage	V_{DS}	600		V
Gate-Source Voltage	V_{GS}		± 30	V
Continuous Drain Current $T_C=25^\circ\text{C}$	I_D	7	7*	A
$T_C=100^\circ\text{C}$		4.8	4.8*	
Pulsed Drain Current ^C	I_{DM}	28		
Avalanche Current ^C	I_{AR}	3		A
Repetitive avalanche energy ^C	E_{AR}	135		mJ
Single pulsed avalanche energy ^G	E_{AS}	270		mJ
MOSFET dv/dt ruggedness	dv/dt	50		V/ns
Peak diode recovery dv/dt		5		
Power Dissipation ^B $T_C=25^\circ\text{C}$	P_D	192	38.5	W
Derate above 25°C		1.54	0.3	W/°C
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150		°C
Maximum lead temperature for soldering purpose 1/8" from case for 5 seconds	T_L	300		°C

Thermal Characteristics

Parameter	Symbol	AOT7N60	AOTF7N60	Units
Maximum Junction-to-Ambient ^{A,D}	$R_{\theta JA}$	65	65	°C/W
Maximum Case-to-sink ^A	$R_{\theta CS}$	0.5	--	°C/W
Maximum Junction-to-Case	$R_{\theta JC}$	0.65	3.25	°C/W

* Drain current limited by maximum junction temperature.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=25^\circ\text{C}$	600			V
		$I_D=250\mu\text{A}, V_{GS}=0\text{V}, T_J=150^\circ\text{C}$		700		
$BV_{DSS}/\Delta T_J$	Zero Gate Voltage Drain Current	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	0.72			$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$		1		μA
		$V_{DS}=480\text{V}, T_J=125^\circ\text{C}$		10		
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 30\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=5\text{V}, I_D=250\mu\text{A}$	3	3.9	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=3.5\text{A}$		1	1.2	Ω
g_{FS}	Forward Transconductance	$V_{DS}=40\text{V}, I_D=3.5\text{A}$		12		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.74	1	V
I_S	Maximum Body-Diode Continuous Current				7	A
I_{SM}	Maximum Body-Diode Pulsed Current				28	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$	685	861	1035	pF
C_{oss}	Output Capacitance		65	84	100	pF
C_{rss}	Reverse Transfer Capacitance		5.2	6.6	7.9	pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	3	4.1	6.2	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=480\text{V}, I_D=7\text{A}$	19.3	23	28	nC
Q_{gs}	Gate Source Charge		3.8	5	5.5	nC
Q_{gd}	Gate Drain Charge		9.3	11.2	13.5	nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=300\text{V}, I_D=7\text{A}, R_G=25\Omega$	25			ns
t_r	Turn-On Rise Time		49.5			ns
$t_{D(off)}$	Turn-Off DelayTime		51.5			ns
t_f	Turn-Off Fall Time		43.5			ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=7\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$	212	255	306	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=7\text{A}, dI/dt=100\text{A}/\mu\text{s}, V_{DS}=100\text{V}$	2.0	2.6	3.1	μC

A. The value of $R_{\theta JA}$ is measured with the device in a still air environment with $T_A=25^\circ\text{C}$.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ\text{C}$.

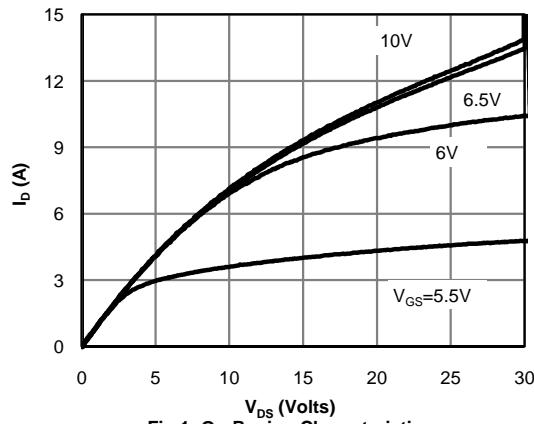
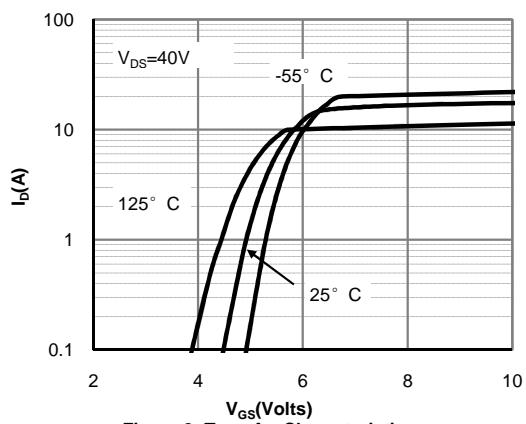
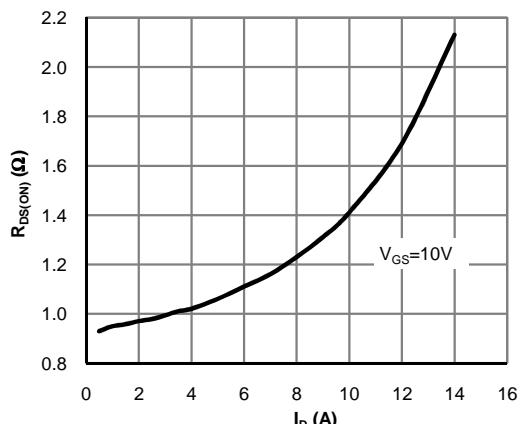
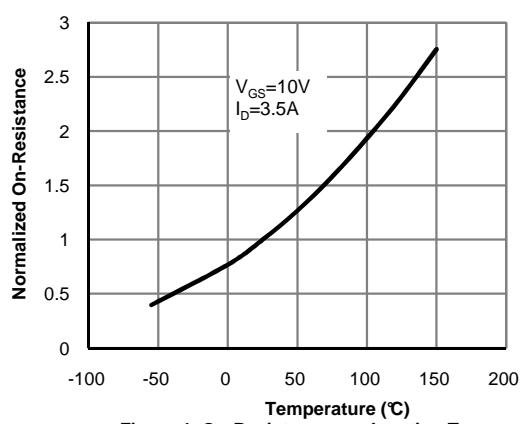
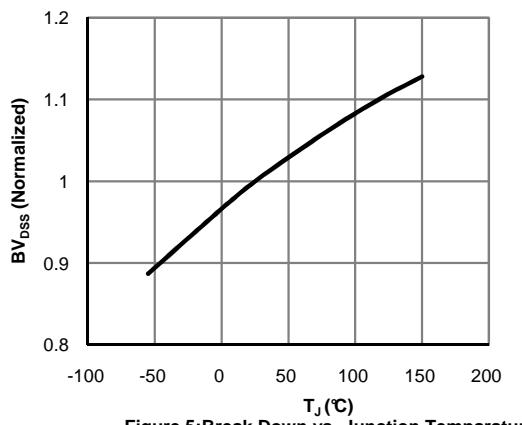
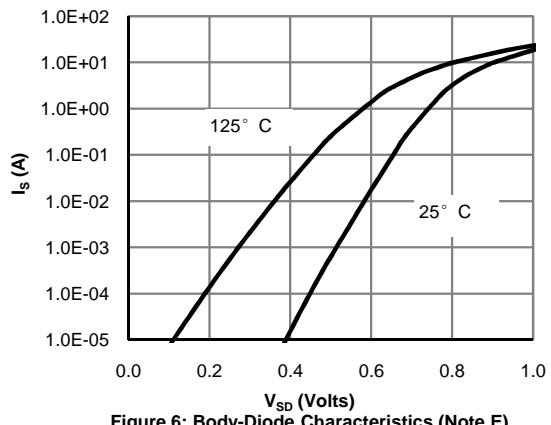
D. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

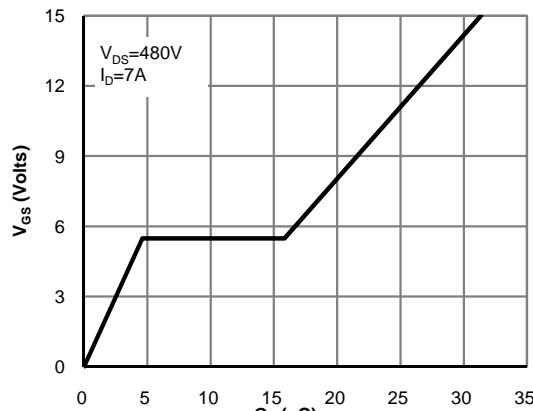
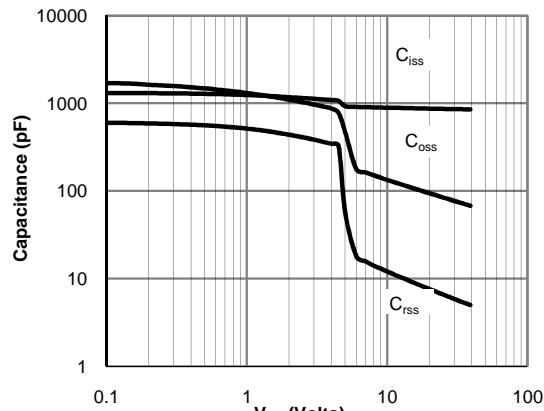
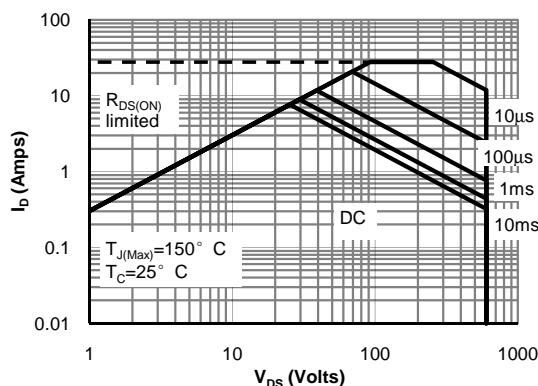
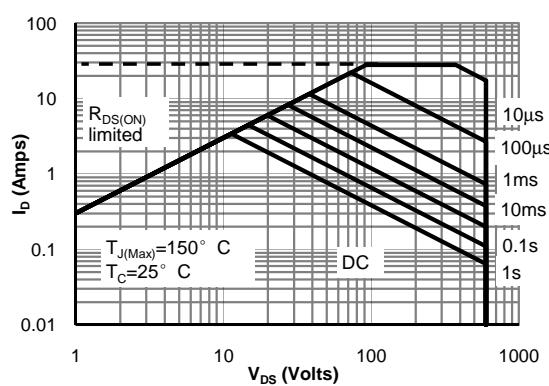
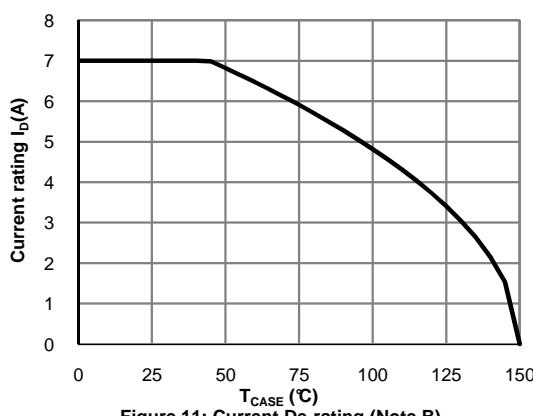
E. The static characteristics in Figures 1 to 6 are obtained using $<300\ \mu\text{s}$ pulses, duty cycle 0.5% max.

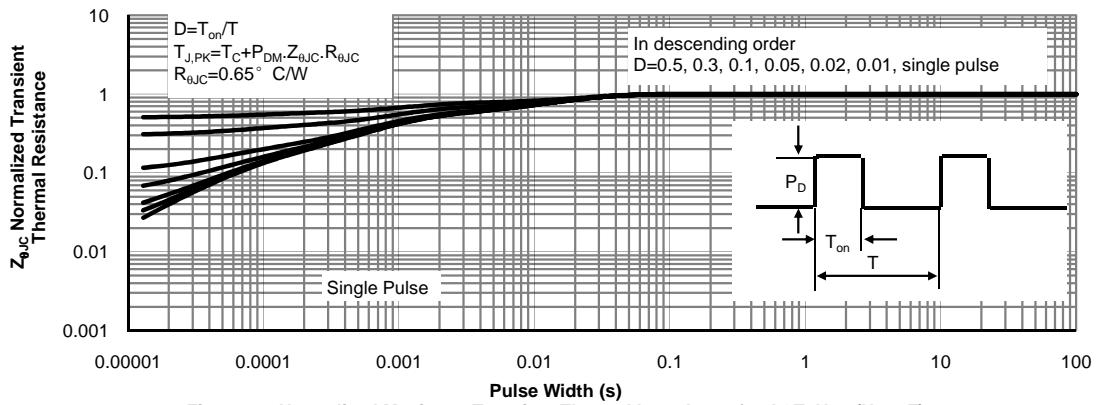
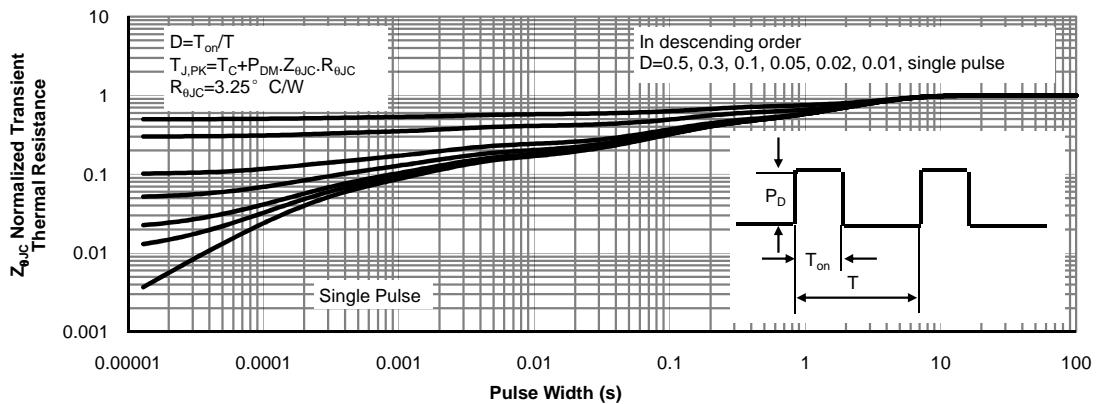
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

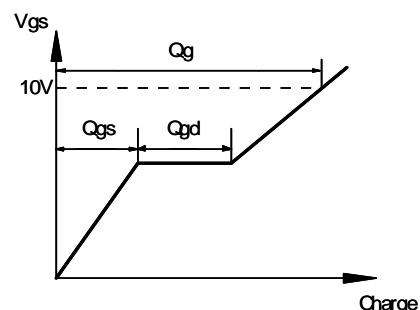
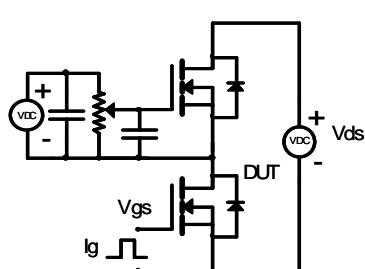
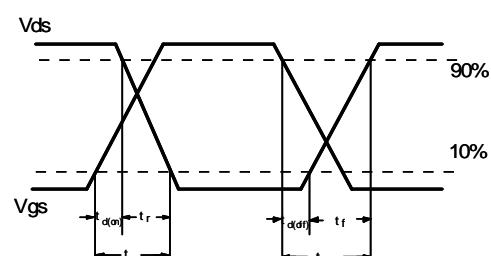
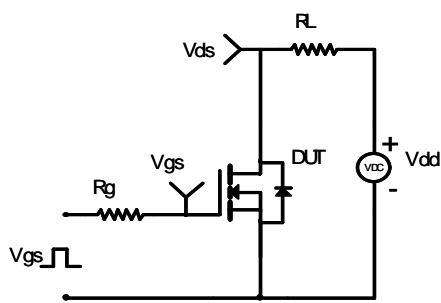
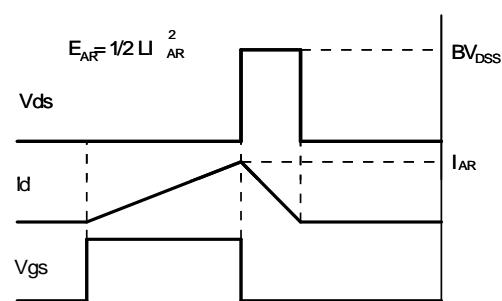
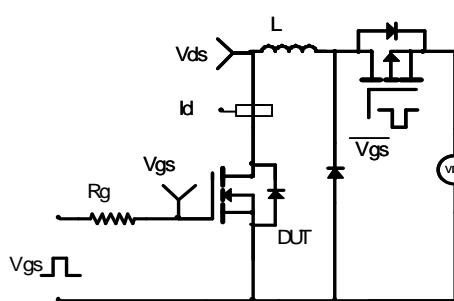
G. $L=60\text{mH}, I_{AS}=3\text{A}, V_{DD}=150\text{V}, R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Fig 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature

Figure 5: Break Down vs. Junction Temperature

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area for AOT7N60 (Note F)

Figure 10: Maximum Forward Biased Safe Operating Area for AOTF7N60 (Note F)

Figure 11: Current De-rating (Note B)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 12: Normalized Maximum Transient Thermal Impedance for AOT7N60 (Note F)

Figure 13: Normalized Maximum Transient Thermal Impedance for AOTF7N60 (Note F)

Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms
